

L Number	Hits	Search Text	DB	Time stamp
1	1238	semiconductor and (die or dice) and (remov\$ or separat\$) and (criteria or test) and (adhesive or glue or paste) and (cure or curing)	USPAT	2004/10/13 07:22
2	52	semiconductor and (die or dice) and (remov\$ or separat\$) and (criteria or test) and (adhesive near5 (liquid or paste)) and (cure or curing) and (lead adj frame)	USPAT	2004/10/13 07:29
3	28	semiconductor and (die or dice) and (remov\$ or separat\$) and (criteria or test) and (adhesive near5 (liquid or paste)) and (cure or curing) and (lead adj frame)	US-PGPUB	2004/10/13 07:29
4	0	semiconductor and (die or dice) and (remov\$ or separat\$) and (criteria or test) and (adhesive near5 (liquid or paste)) and (cure or curing) and (lead adj frame)	EPO	2004/10/13 07:29
5	0	semiconductor and (die or dice) and (remov\$ or separat\$) and (criteria or test) and (adhesive near5 (liquid or paste)) and (cure or curing) and (lead adj frame)	JPO	2004/10/13 07:29
6	0	semiconductor and (die or dice) and (remov\$ or separat\$) and (criteria or test) and (adhesive near5 (liquid or paste)) and (cure or curing) and (lead adj frame)	IBM_TDB	2004/10/13 07:29
7	0	semiconductor and (die or dice) and (remov\$ or separat\$) and (criteria or test) and (adhesive near5 (liquid or paste)) and (cure or curing) and (lead adj frame)	DERWENT	2004/10/13 07:29